

Power Inductor

AHP30135BMV-SERIES

1、Features

1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
3. High reliability -Reliability tests comply with AEC-Q200

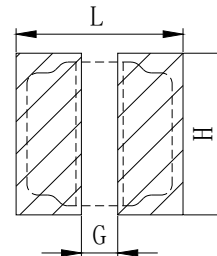
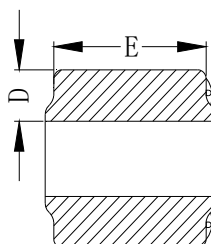
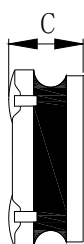
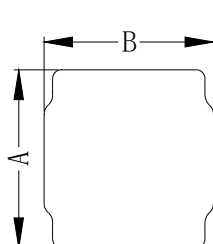

AEC-Q200


2、Applications

Automotive applications.

Recommended Land pattern

3、Dimension



Series	*A(mm)	*B(mm)	*C(mm)	D(mm)	E(mm)
AHP30135	3.0 ± 0.2	3.0 ± 0.2	1.15 ± 0.2	0.9 ± 0.3	2.7 ± 0.3

*Dimensions are not including the termination. For maximum overall dimensions with termination, add 0.1mm.

L(mm)	G(mm)	H(mm)
3.5	0.9	3.5

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.10mm and above.

4、Part Numbering

AHP **30135** **BM** **V** - **1R0** - **M**

A B C D E F

A: Series

B: Dimension

C: Type

D: Code

E: Inductance

F: Inductance Tolerance

V=Vehicle

1R0=1.00uH

K=±10%, L=±15%, M=±20%, Y=±30%.

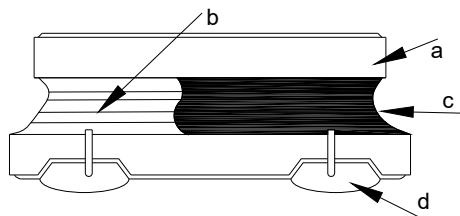
5、Specification

TAI-TECH Part Number	Inductance L0 A(uH)	I rms (A)		I sat (A)		DCR (mΩ)	
		Typ	max	typ	max	typ	max
AHP30135BMV-R47M	0.47	5.60	4.80	9.80	8.90	28	34
AHP30135BMV-1R0M	1.00	4.50	3.90	7.50	6.90	42.5	47
AHP30135BMV-1R5M	1.50	3.80	3.40	6.70	6.10	58	70
AHP30135BMV-2R2M	2.20	3.30	2.90	5.70	5.30	81	97
AHP30135BMV-3R3M	3.30	2.70	2.40	4.50	4.10	130	156
AHP30135BMV-4R7M	4.70	2.20	1.90	3.90	3.50	180	216
AHP30135BMV-6R8M	6.80	1.90	1.60	3.00	2.60	252	303
AHP30135BMV-100M	10.0	1.30	1.00	2.40	2.00	445	535

Note:

1. Test frequency : L_s : 1MHz /1.0V.
2. All test data referenced to 25℃ ambient.
3. Testing Instrument(or equ) : Agilent 4284A, E4991A, 4339B, KEYSIGHT E4980A/AL, chroma3302, 3250, 16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃ under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.
Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of Irms and Isat.

6、Material List



NO	Items	Materials
a	Core	Alloy Powder
b	Wire	Enameled Copper Wire
c	Glue	Epoxy with magnetic powder
d	Terminal	Ag/Ni/Sn+ Sn Solder

11、Typical Performance Curves

